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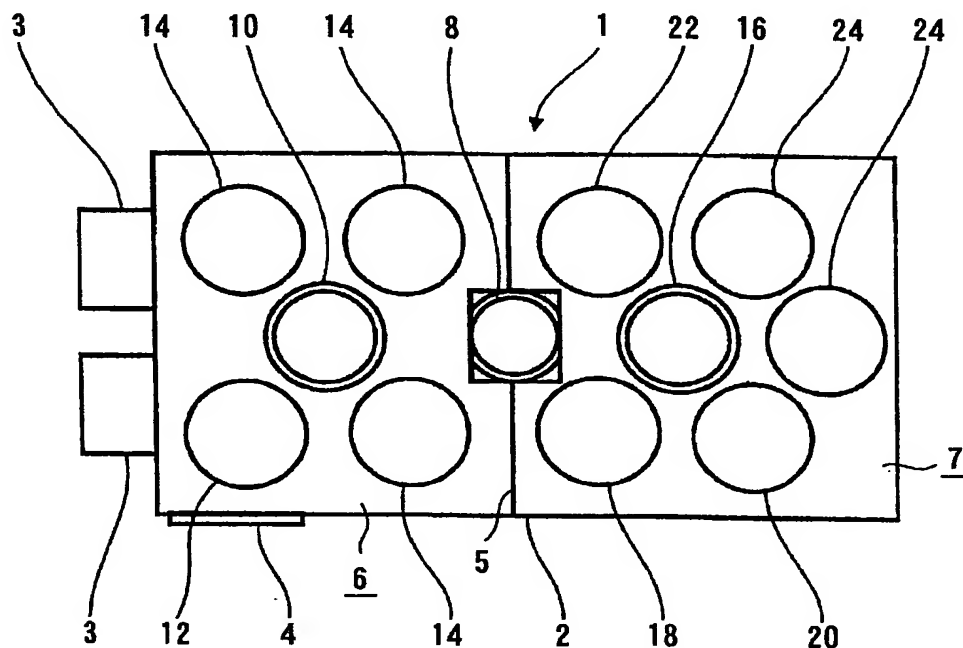
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(54) Title: PLATING METHOD AND APPARATUS



(57) Abstract: A plating apparatus (1) has a steam treatment chamber (18) configured to perform a steam treatment using steam on a surface of a substrate (W), and a plating chamber (24) configured to plate the surface of the substrate subjected to the steam treatment. The plating apparatus also has an acid treatment chamber (20) configured to bring the surface of the substrate subjected to the steam treatment into contact with an acid liquid. The plating apparatus includes a frame (2) housing the steam treatment chamber (18), the acid treatment chamber (20), and the plating chamber (24).

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